

**Analog Sound Processor Series** 

# 6ch Sound Processor for High-Quality Audio with Built-in Advanced Switch

#### BD34602FS-M

#### Description

BD34602FS-M is a 6ch independent volume system. It is designed to have high-quality sound by improving the op-amp and optimizing the design layout. In addition, it is compatible, same package and it has common control with BD3461FS, therefore replacement from BD3461FS is easy.

#### Features

- AEC-Q100 Qualified<sup>(Note 1)</sup>
- Advanced switch circuit can reduce the switching pop noise during volume attenuation
- Built-in 6ch independent volume circuit available with changing by 1dB/Step
- Built-in DIFF amplifier inputs, ideal for external input
- Built-in volume circuit for mixing external signal available with changing by 1dB/Step
- Package is SSOP-A24. Putting input-terminals together and output-terminals together can make PCB layout easier and can makes area of PCB smaller.
- It is possible to control by 3.3V for I<sup>2</sup>C-BUS Controller
- (Note1 : Grade 3)

#### Applications

Suitable for the Car Audio systems, Car Navigation systems.

#### **Typical Application Circuit**

#### Key Specifications

Total harmonic distortion :	0.0004%
Maximum input voltage :	2.35Vrms(Typ)
Maximum output voltage :	2.35Vrms(Typ)
Output noise voltage :	1.3µVrms(Typ)
Residual output noise voltage :	1.3µVrms(Typ)
Ripple rejection :	80dB (Typ)
Operating temperature range :	-40°C to +85°C

Package SSOP-A24 W(Typ) x D(Typ) x H(Max) 10.00mm x 7.80mm x 2.10mm





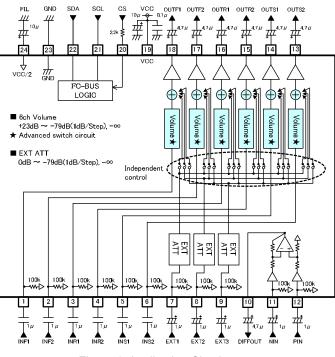


Figure 1. Application Circuit

OProduct structure:Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays

#### **Pin Configuration**

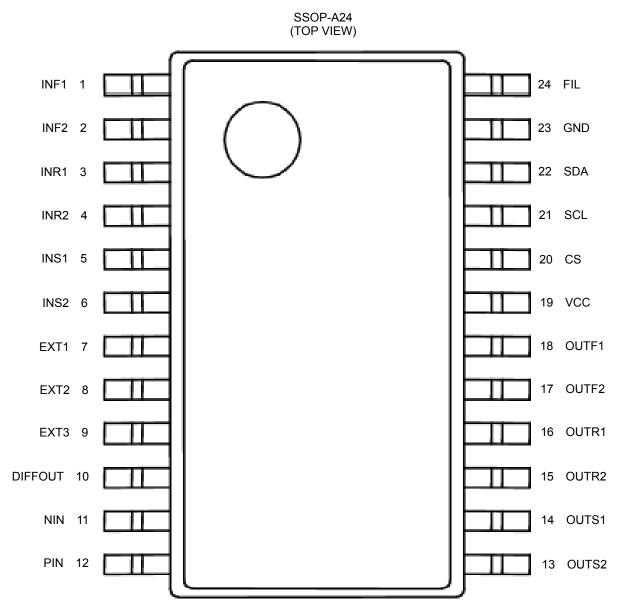


Figure 2. Pin Configuration

Terminal No.	Terminal Name	Description	Terminal No.	Terminal Name	Description
1	INF1	Front input terminal of 1ch	13	OUTS2	Subwoofer output terminal of 2ch
2	INF2	Front input terminal of 2ch	14	OUTS1	Subwoofer output terminal of 1ch
3	INR1	Rear input terminal of 1ch	15	OUTR2	Rear output terminal of 2ch
4	INR2	Rear input terminal of 2ch	16	OUTR1	Rear output terminal of 1ch
5	INS1	Subwoofer input terminal of 1ch	17	OUTF2	Front output terminal of 2ch
6	INS2	Subwoofer input terminal of 2ch	18	OUTF1	Front output terminal of 1ch
7	EXT1	External input terminal of 1ch	19	VCC	Power supply terminal
8	EXT2	External input terminal of 2ch	20	CS	Chip select terminal
9	EXT3	External input terminal of 3ch	21	SCL	I <sup>2</sup> C-BUS clock terminal
10	DIFFOUT	DIFF amp output terminal	22	SDA	I <sup>2</sup> C-BUS data terminal
11	NIN	DIFF amp negative input terminal	23	GND	GND terminal
12	PIN	DIFF amp positive input terminal	24	FIL	VCC/2 terminal

### Descriptions of terminal

#### Block diagram

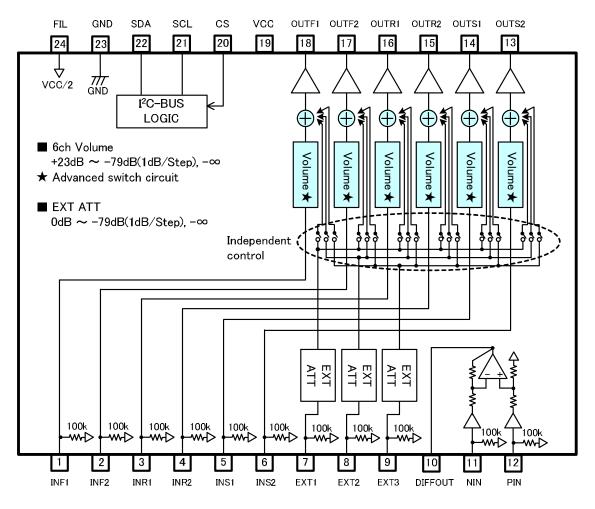


Figure 3. Block diagram

- The audible signal inputted from 1pin to 6pin are adjusted independently in volume block, and outputted from 13pin to 18pin.
- The audible signal inputted from 7pin to 9pin are adjusted independently in EXT ATT block, and added independently to the audible signal inputted from 1pin to 6pin in EXT ON/OFF block, and outputted from 13pin to 18pin.

#### Absolute maximum ratings (Ta=25°C)

Item	Symbol	Ratings	Unit
Power supply Voltage	VCC MAX	10	V
Input voltage	Pd	1.0 (Note1)	W
Input voltage	Vin	GND-0.3 to VCC+0.3	V
Operating Temperature	Topr	-40 to +85	°C
Storage Temperature	Tstg	-55 to +150	°C

 (Note 1)
 SSOP-A24:Derating at 8.0mW/°C for operating above Ta≥25°C (mounted on 70×70×1.6mm ROHM standard board)

 (Note 2)
 If it is within the operating voltage range, circuit functions and operation are guaranteed within this operating temperature.

**Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

#### **Operating Range**

 lange					
Item	Symbol	MIN	TYP	MAX	Unit
Power Supply	VCC	7.0	8.5	9.5	V

#### Electrical characteristic

(Unless otherwise specified, Ta=25°C, VCC=8.5V, f=1kHz, Vin=1Vrms, RL=10kΩ, INF1, INF2 Input, Volume=0dB)

	otherwise specified, Ta=25°C, VC	C=0.5V, I= IK	.⊓∠, vin= i		- 10K12, 11NI	- I, IINFZ II	iput, volume=0dB)
BLOCK	Item	Symbol	Min	Limit Typ	Max	Unit	Conditions
	Circuit Current upon no signal	IQ	_	35	50	mA	No signal
	Voltage gain	Gv	-0.5	0	0.5	dB	G <sub>V</sub> =20log(VOUT/VIN)
	Channel balance	СВ	-0.5	0	0.5	dB	CB=G <sub>V1CH</sub> -G <sub>V2CH</sub>
	Total harmonic distortion	THD+N 1k		0.0004	0.05	%	VOUT=1Vrms, f=1kHz BW=400-30kHz
ZAL	+ Noise	THD+N 10k	_	0.002	0.05	%	VOUT=1Vrms, f=10kHz BW=400-80kHz
GENERAL	Output noise voltage	V <sub>NO</sub>	_	1.3	9	µVrms	Rg=0Ω, BW=IHF-A ∗
0	Residual output noise voltage	V <sub>NOR</sub>	-	1.3	9	µVrms	Volume=-∞ Rg=0, BW=IHF-A ∗
		CTC1k	_	-109	-90	dB	Rg=0Ω, BW=IHF-A * CTC1k=20log(VOUT/VIN) f=1kHz
	Cross-talk between channels	CTC10k		-103	-90	dB	Rg=0Ω, BW=400-80kHz CTC10k=20log(VOUT/VIN) f=10kHz
	Ripple rejection	RR	55	80		dB	f=100Hz, VCCIN=100mVrms RR=20log(VCCIN/VOUT)
	Input impedance	R <sub>IN V</sub>	70	100	130	kΩ	
	Maximum input voltage	V <sub>IM1k</sub>	2	2.35	_	Vrms	VIM at THD+N(VOUT)=1% BW=400-30kHz, f=1kHz
		V <sub>IM10k</sub>	2	2.35	_	Vrms	VIM at THD+N(VOUT)=1% BW=400-80kHz, f=10kHz
	Maximum gain	G <sub>V BST</sub>	22	23	24	dB	Gain=23dB, VIN=100mVrms G <sub>V BST</sub> =20log(VOUT/VIN)
	Maximum attenuation	G <sub>V MIN1k</sub>	_	-109	-90	dB	Volume=-∞ G <sub>V MIN1k</sub> =20log(VOUT/VIN) BW=IHF-A∗, f=1kHz
Æ		G <sub>V MIN10k</sub>	-	-103	-90	dB	Volume=-∞ G <sub>V MIN10k</sub> =20log(VOUT/VIN) BW=400-80kHz, f=10kHz
OLUME	Gain set error	G <sub>V ERR</sub>	-1.0	0	1.0	dB	Gain=+1~+23dB
>	Attenuation set error 1	G <sub>V ERR1</sub>	-0.5	0	0.5	dB	ATT=-1~-15dB
	Attenuation set error 2	G <sub>V ERR2</sub>	-1.0	0	1.0	dB	ATT=-16~-47dB
	Attenuation set error 3	G <sub>V ERR3</sub>	-2.0	0	2.0	dB	ATT=-48~-79dB
	Output impedance	R <sub>OUT</sub>	70	100	130	Ω	Vin=100mVrms
	Maximum output voltage	V <sub>OM1k</sub>	2	2.35	_	Vrms	THD+N=1% BW=400-30kHz, f=1kHz
		V <sub>OM10k</sub>	2	2.35	_	Vrms	THD+N=1% BW=400-80kHz, f=10kHz
EXT ATT	Input impedance	R <sub>IN M</sub>	70	100	130	kΩ	
ЩA	Maximum attenuation	G <sub>M MIN</sub>	_	-90	-80	dB	G <sub>M MIN</sub> =20log(VOUT/VIN) BW=IHF-A ∗ , ATT=-∞
L.	Input impedance	R <sub>IN D</sub>	70	100	130	kΩ	
DIFF	Common mode rejection ratio	CMRR	50	65	—	dB	PIN and NIN input CMRR=20log10(VIN/VOUT) BW=IHF-A *

Phase between input / output is same

\* VP-9690(Average value detection, effective value display) filter by Panasonic is used for \* measurement.

Typical Performance Curve(s)

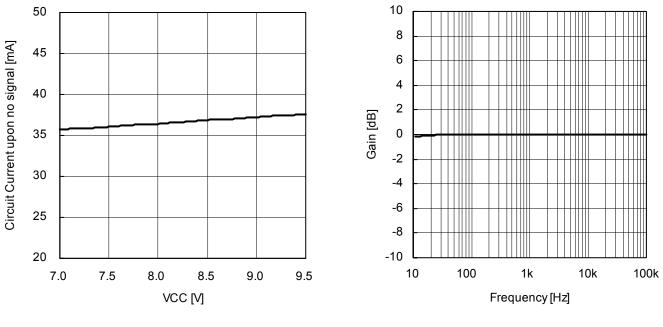


Figure 4. VCC vs Circuit Current upon no signal

Figure 5. Gain vs Frequency

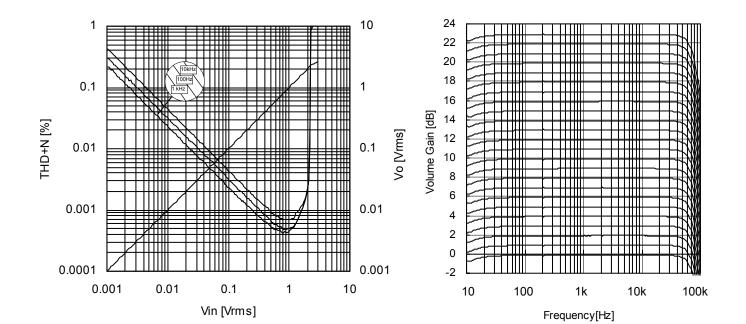
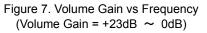
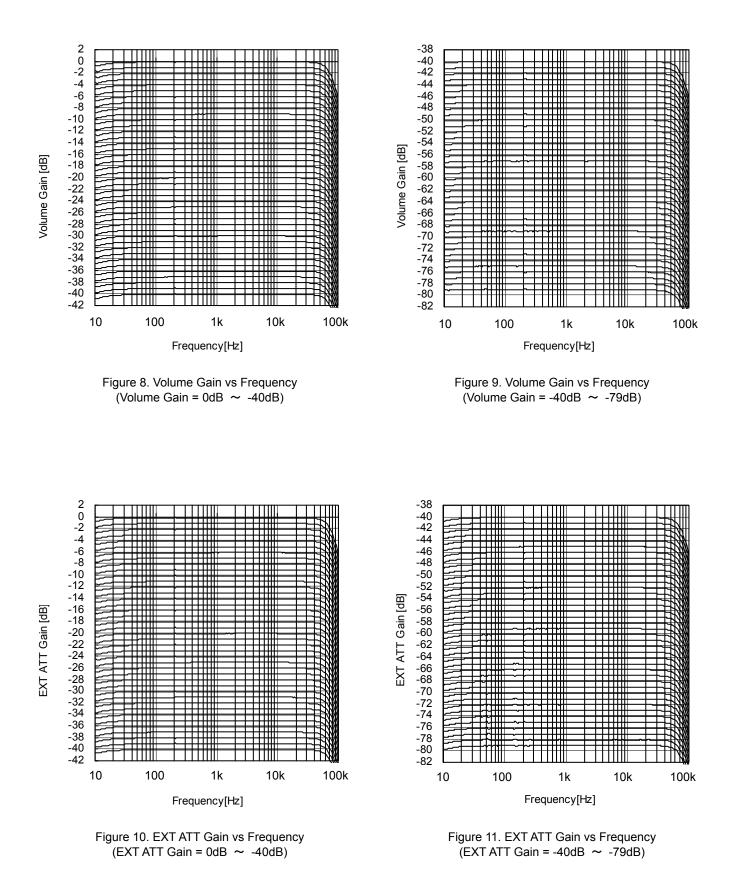


Figure 6. THD+N vs VIN / Vo





(Note) The measurement results of Figure 7 to Figure 11 used by 80kHz LPF.

#### **CONTROL SIGNAL SPECIFICATION**

(1) Electrical specifications and timing for bus lines and I/O stages

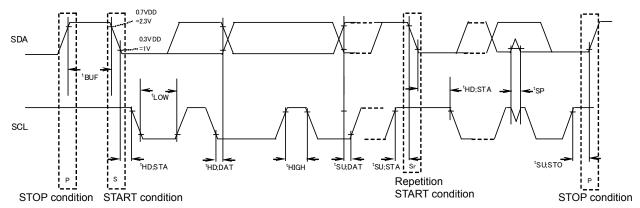


Figure 12. Definition of timing on the I<sup>2</sup>C-BUS

	Item	Symbol	Fast-mode	I <sup>2</sup> C-BUS)	Unit
	Item	Symbol	Min	Max	Unit
1	SCL clock frequency	fSCL	0	400	kHz
2	Bus free time between a STOP and START condition	tBUF	1.3	—	μs
3	Hold time (repeated) START condition. After this period, the first clock pulse is generated	tHD;STA	0.6	_	μs
4	LOW period of the SCL clock	tLOW	1.3	—	μs
5	HIGH period of the SCL clock	tHIGH	0.6	—	μs
6	Set-up time for a repeated START condition	tSU;STA	0.6	—	μs
7	Data hold time	tHD;DAT	0	—	μs
8	Data set-up time	tSU;DAT	100	—	ns
9	Set-up time for STOP condition	tSU;STO	0.6	—	μs

All values referred to VIH min. and VIL max. Levels (see Table 2).

#### Table 2 Input/Output Characteristics of the SDA and SCL terminal for I<sup>2</sup>C-BUS devices

	Item	Symbol	Fast-mode	Unit	
		Symbol	Min	Max	Onit
10	LOW level input voltage	V <sub>IL</sub>	-0.5	1	V
11	HIGH level input voltage	VIH	2.3	-	V
12	Pulse width of spikes which must be suppressed by the input filter.	tSP	0	50	ns
13	LOW level output voltage : At 3mA sink current	V <sub>OL1</sub>	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5 VDDmax.	li	-10	10	μA

#### Table 3 Input Characteristics of the CS terminal (Slave Address can be changed by the setting of CS terminal)

	Item	Symbol	Min	Max	Unit
1	CS = Low : Slave Address 80 hex	V <sub>CSL</sub>	-0.5	1	V
2	CS = High : Slave Address 84 hex	V <sub>CSH</sub>	2.3	VCC	V

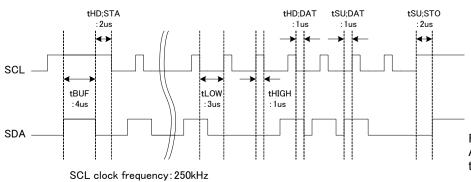


Figure 13. A command timing example in the I<sup>2</sup>C-BUS data transmission

#### (2) I<sup>2</sup>C-BUS FORMAT

_		MSB LSB		MSB LS	В	MSB	LSB	
	S	Slave Address	А	Select Address	А	Data	А	Р
-	1bit	8bit	1bit	8bit	1bit	8bit	1bit	1bit
		S	= Sta	art conditions (Recogr	ition o	f start bit)		
	Slave Address = Recognition of Slave Address. 7 bits in upper order are voluntary							itary.
	The least significant bit is "L" due to writing.							
		А	= AC	KNOWLEDGE bit (Re	ecognit	ion of acknowledg	gement)	
		Select Address	= Se	lect every of volume,	bass a	nd treble.		
		Data	= Da	ta on every volume a	nd tone	<b>)</b> .		
		Р	= Sto	op condition (Recogni	ion of	stop bit)		

(3) I<sup>2</sup>C-BUS Interface Protocol

I) Basic Iom	1)	Basic form
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S	Slave Addr	ress	А	Select Ad	ldress	А	Da	ata	А	Ρ
	MSB	LSB		MSB	LSB	М	SB	LSE	3	

2) Automatic increment (For an assigned Select Address increases (+1) according to the number of data.)

S	Slave Address	А	Select Addr	ress	А	Data1	А	Data2	А	 DataN	А	Ρ	
	MSB LS	3	MSB	LSB		MSB	LSB	MSB	LSB	MSB	L	SB	

No.1. Data1 is set as data of address specified by Select Address.

No.2. Data2 is set as data of next address from the address specified by No.1.

No.3. DataN is set as data of address incremented N-1 times from the address specified by No.1.

The Select Address is circulated by the automatic increment function, as shown below (hex).

$$\rightarrow 01 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C \rightarrow 2D \rightarrow 30 \rightarrow 31 \rightarrow 32 \rightarrow 33 \rightarrow 34 \rightarrow 35$$

3) Configuration unavailable for transmission (In this case, only Select Address1 is set.

S	Slave Address	А	Select A	ddress1	А	Data	А	Select /	Address 2	А	Da	ata	А	Ρ
	MSB LSB		MSB	LSB	Μ	SB LS	В	MSB	LSB	Μ	SB	LSE	3	

(Note) If any data is transmitted as Select Address 2 next to data, it is recognized as data, not as Select Address 2.

#### (4) Slave Address

Because the Slave Address can be changed by the setting of CS, it is possible to use two chips at the same time on identical BUS.

CS Terminal Voltage Condition	A6	A5	A4	A3	A2	A1	A0	R/W	Hex
CS = Low : -0.5V to 1.0V	1	0	0	0	0	0	0	0	80
CS = High : 2.3V to VCC	1	0	0	0	0	1	0	0	84

Establish the voltage of CS terminal in the condition to have been defined.

#### (5) Select Address & Data

Items to be set	Select Address	MSB			D	ata			LSB		
items to be set	(hex)	D7	D6	D5	D4	D3	D2	D1	D0		
EXT ATT 1dB/Step Enable	01	0	0	0	0	EXT ATT 1dB/Step Enable	1	0	0		
Advanced Switch Time of EXT ON/OFF	02	0		vanced Sw Time of KT ON/OFF		Advanced Time EXT ON	e of	0	0		
Volume Gain Front 1ch (F1)	28				Volume (	Gain (F1)					
Volume Gain Front 2ch (F2)	29				Volume (	Gain (F2)					
Volume Gain Rear 1ch (R1)	2A		Volume Gain (R1)								
Volume Gain Rear 2ch (R2)	2B		Volume Gain (R2)								
Volume Gain Subwoofer 1ch (S1)	2C				Volume (	Gain (S1)					
Volume Gain Subwoofer 2ch (S2)	2D				Volume (	Gain (S2)					
EXT1 ON/OFF	30	EXT1 S2	EXT1 S1	EXT1 R2	EXT1 R1	EXT1 F2	EXT1 F1	0	0		
EXT2 ON/OFF	31	EXT2 S2	EXT2 S1	EXT2 R2	EXT2 R1	EXT2 F2	EXT2 F1	0	0		
EXT3 ON/OFF	32	EXT3 S2	EXT3 S1	EXT3 R2	EXT3 R1	EXT3 F2	EXT3 F1	0	0		
EXT 1 ATT Gain	33				EXT1 A	TT Gain					
EXT 2 ATT Gain	34				EXT2 A	TT Gain					
EXT 3 ATT Gain	35				EXT3 A	TT Gain					
Test Mode	F0	0	0	0	0	0	0	0	0		
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

Note(Please be sure to follow the instructions)

It is written with "0", "1" by the above table, please set "0", "1" in the same way as above table.

In case of different settings, there is possibility of cause unintended behavior.

#### Instructions of the data format

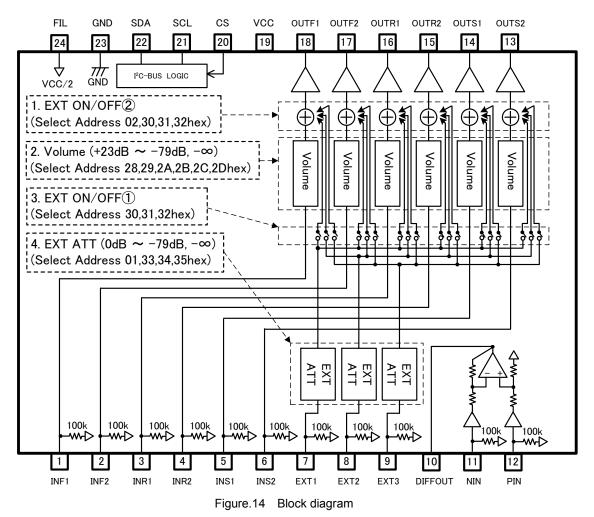
- 1. In function changing of the hatching part, it works Advanced switch(In detail, please refer p13).
- 2. Upon continuous data transfer, the Select Address is circulated by the automatic increment function, as shown below(hex).

$$\rightarrow 01 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C \rightarrow 2D \rightarrow 30 \rightarrow 31 \rightarrow 32 \rightarrow 33 \rightarrow 34 \rightarrow 35$$

#### %Select Address 02(hex) is not included in the automatic increment to keep BD3461FS software compatible.

3. When changing "EXT = ON/OFF", it is not corresponded for advance switch. Therefore, please do the measure that applies mute on the side of a set at the time of these setting changes

Explanation of each Select Address



It is able to control to 1 to 4 in block diagram by each Select Address. About detail explanation is Follow as.

- The audible signal inputted from 1pin to 6pin are adjusted independently in volume block(2 in block diagram).
- < Select Address 28, 29, 2A, 2B, 2C 2D(hex) : Volume > It is able to select adjustment of audible signal in volume block(+23dB to -79dB, -∞).
- The audible signal inputted from 7pin to 9pin are adjusted independently in EXT ATT block(4 in block diagram), and added independently to the audible signal inputted from 1pin to 6pin in EXT ON/OFF block. (EXT ON/OFF① block (3 in block diagram) : path select, EXT ON/OFF② block (1 in block diagram) : add)
- < Select Address 01(hex) : EXT ATT 1dB/Step Enable > About adjustment of audible signal in EXT ATT block (4 in block diagram), it is able to select 1dB/Step mode ON/OFF.
- < Select Address 02(hex) : Advanced Switch Time of EXT ON/OFF > Advanced Switch function is applied to EXT ON/OFF for prevention switching pop-noise. (About Advanced Switch, refer to 15page) It is able to select switching time of Advanced Switch by Select Address 02(hex).
- < Select Address 30, 31, 32(hex) : EXT ON/OFF > The audible signal inputted from 7pin to 9pin is added to the audible signal inputted from 1pin to 6pin. It is able to select path of above combination (1 and 3 in block diagram).
- < Select Address 33, 34, 35(hex) : EXT ATT > It is able to select adjustment (0dB to -79dB, -∞) of audible signal in EXT ATT block (3 in block diagram).

#### Select Address 01(hex) EXT ATT 1dB/Step Enable

MODE	MSB		E	EXT ATT 1dB	S/Step Enable	)		LSB
MODE	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	0	0	0	0	0	0
ON	0	0	0	0	1	U	0	0

#### Select Address 02(hex) Advanced Switch Time of EXT ON/OFF

MODE	MSB		Advance	ed Switch Tir	ne of EXT O	N/OFF 1		LSB
NIODE	D7	D6	D5	D4	D3	D2	D1	D0
11.2msec					0	0		
4.7msec	0	Ac	dvanced Swit	ch	0	1	0	0
7.2msec	0	Time	of EXT ON/0	OFF 2	1	0	0	0
14.4msec					1	1		

#### Select Address 02(hex) Advanced Switch Time of EXT ON/OFF

MODE	MSB		Advance	ed Switch Tir	ne of EXT O	N/OFF 2		LSB			
MODE	D7	D6	D5	D4	D3	D2	D1	D0			
x1		0	0	0							
x2		0	0	1							
x3		0	1	0							
x4	0	0	1	1		ed Switch	0	0			
x5	0	1	0	0	EXT ON	e of	0	0			
x6		1	0	1							
x7		1	1	0	1						
x8		1	1	1							

#### Select Address 28, 29, 2A, 2B, 2C 2D(hex) Volume

Gain & ATT	MSB			Volume Gair	h/Attenuation			LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
Prohibition ※	0	0	0	0	0	0	0	1
FIUNDUUT %	:	:	:	:	:	:	:	:
	0	1	1	0	1	0	0	0
23dB	0	1	1	0	1	0	0	1
22dB	0	1	1	0	1	0	1	0
21dB	0	1	1	0	1	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition 💥	:	:		•	•		:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

: Initial condition

Select Address 30, 31	, 32(hex)	EXT ON/OFF	-					
MODE	MSB			EXT	「F1			LSB
MODE	D7	D6	D5	D4	D3	D2	D1	D0
OFF	EXT	EXT	EXT	EXT	EXT	0		
ON	S2	S1	R2	R1	F2	1	0	0
	•	•	•	•	•	•	•	
MODE	MSB			EX1	T F2			LSB
MODE	D7	D6	D5	D4	D3	D2	D1	D0
OFF	EXT	EXT	EXT	EXT	0	EXT	0	0
ON	S2	S1	R2	R1	1	F1	0	0
MODE	MSB			EXT	<sup>-</sup> R1			LSB
	D7	D6	D5	D4	D3	D2	D1	D0
OFF	EXT	EXT	EXT	0	EXT	EXT	0	0
ON	S2	S1	R2	1	F2	F1	0	0
MODE	MSB			EXT	<sup>-</sup> R2			LSB
NIODE	D7	D6	D5	D4	D3	D2	D1	D0
OFF	EXT	EXT	0	EXT	EXT	EXT	0	0
ON	S2	S1	1	R1	F2	F1	0	0
MODE	MSB			EX	Г S1			LSB
	D7	D6	D5	D4	D3	D2	D1	D0
OFF	EXT	0	EXT	EXT	EXT	EXT	0	0
ON	S2	1	R2	R1	F2	F1	0	0
MODE	MSB			EXT	- S2			LSB
NIODE	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	EXT	EXT	EXT	EXT	EXT	0	0
ON	1	S1	R2	R1	F2	F1	U	U

#### Select Address 30, 31, 32(hex) FXT ON/OFF

Select Address 33, 34, 35(hex) EXT ATT % Select Address 01(hex), D3 = 0, (EXT 1dB Enable = OFF)

Gain	MSB		EXT Attenuation								
Gain	D7	D6	D5	D4	D3	D2	D1	D0			
0dB						0	0	0			
-8dB						0	0	1			
-16dB						0	1	0			
-24dB	0	0	0	0	0	0	1	1			
-32dB	U	0	0	0	0	1	0	0			
-48dB						1	0	1			
-64dB						1	1	0			
-∞dB						1	1	1			

Select Address 33, 34, 35(hex) EXT ATT Select Address 01(hex), D3 = 1, (EXT 1dB Enable = ON)

Gain & ATT	MSB			EXT Atte	enuation			LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
0dB	1	0	0	0	0	0	0	0
-1dB	1	0	0	0	0	0	0	1
-2dB	1	0	0	0	0	0	1	0
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	1	0
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition 💥	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
-∞	1	1	1	1	1	1	1	1

: Initial condition 

#### (6) About power on reset

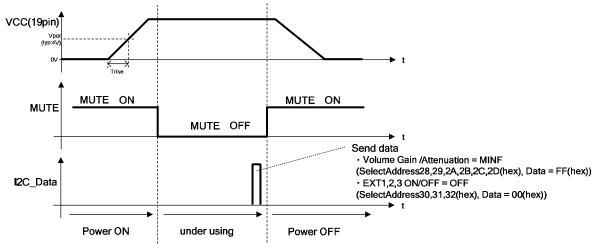
At on of supply voltage circuit made initialization inside IC is built-in. Please send data to all address as initial data at supply voltage on. And please supply mute at set side until this initial data is sent.

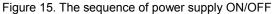
Item	Symbol		Limit		Unit	Condition
nem	Oymbol	Min Typ Max		Onic	Condition	
Rise time of VCC	Trise	33	—	—	$\mu \sec$	VCC rise time from 0V to 5V
VCC voltage of release power on reset	Vpor	_	4.1	_	V	

(7) About start-up and power off sequence on IC

In power supply off, please set a register state of the IC as follows.

- Volume Gain /Attenuation = MINF (SelectAddress28,29,2A,2B,2C,2D(hex), Data = FF(hex))
- EXT1,2,3 ON/OFF = OFF (SelectAddress30,31,32(hex), Data = 00(hex))





- Select Address 28, 29, 2A, 2B, 2C 2D(hex) Volume (Gain = +23dB ~ -79dB, - $\infty$ ) Select Address 33, 34, 35(hex) EXT ATT (Gain = 0dB ~ -79dB, - $\infty$ )
- Select Address 01(hex), D3 = 1, (EXT 1dB Enable = ON)

Volume gain attenuation

Volume gai				<b>D</b> 4	DO	<b>D</b> 0	<b>D</b> 4	50		<b>D -</b>	50	<b>D</b> =	<b>D</b> 4		50	54	
(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+23	0	1	1	0	1	0	0	1	-29	1	0	0	1	1	1	0	1
+22	0	1	1	0	1	0	1	0	-30	1	0	0	1	1	1	1	0
+21	0	1	1	0	1	0	1	1	-31	1	0	0	1	1	1	1	1
+20	0	1	1	0	1	1	0	0	-32	1	0	1	0	0	0	0	0
+19	0	1	1	0	1	1	0	1	-33	1	0	1	0	0	0	0	1
+18	0	1	1	0	1	1	1	0	-34	1	0	1	0	0	0	1	0
+17	0	1	1	0	1	1	1	1	-35	1	0	1	0	0	0	1	1
+16	0	1	1	1	0	0	0	0	-36	1	0	1	0	0	1	0	0
+15	0	1	1	1	0	0	0	1	-37	1	0	1	0	0	1	0	1
+14	0	1	1	1	0	0	1	0	-38	1	0	1	0	0	1	1	0
+13	0	1	1	1	0	0	1	1	-39	1	0	1	0	0	1	1	1
+12	0	1	1	1	0	1	0	0	-40	1	0	1	0	1	0	0	0
+11	0	1	1	1	0	1	0	1	-41	1	0	1	0	1	0	0	1
+10	0	1	1	1	0	1	1	0	-42	1	0	1	0	1	0	1	0
+9	0	1	1	1	0	1	1	1	-43	1	0	1	0	1	0	1	1
+9	0	1	1	1	1	0	0	0	-43	1	0	1	0	1	1	0	0
+0 +7	0	1	1	1	1	0	0	1	-44 -45	1	0	1	0	1	1	0	1
	-	1				-				1	-			1	1	-	
+6	0		1	1	1	0	1	0	-46	-	0	1	0		-	1	0
+5	0	1	1	1	1	0	1	1	-47	1	0	1	0	1	1	1	1
+4	0	1	1	1	1	1	0	0	-48	1	0	1	1	0	0	0	0
+3	0	1	1	1	1	1	0	1	-49	1	0	1	1	0	0	0	1
+2	0	1	1	1	1	1	1	0	-50	1	0	1	1	0	0	1	0
+1	0	1	1	1	1	1	1	1	-51	1	0	1	1	0	0	1	1
0	1	0	0	0	0	0	0	0	-52	1	0	1	1	0	1	0	0
-1	1	0	0	0	0	0	0	1	-53	1	0	1	1	0	1	0	1
-2	1	0	0	0	0	0	1	0	-54	1	0	1	1	0	1	1	0
-3	1	0	0	0	0	0	1	1	-55	1	0	1	1	0	1	1	1
-4	1	0	0	0	0	1	0	0	-56	1	0	1	1	1	0	0	0
-5	1	0	0	0	0	1	0	1	-57	1	0	1	1	1	0	0	1
-6	1	0	0	0	0	1	1	0	-58	1	0	1	1	1	0	1	0
-7	1	0	0	0	0	1	1	1	-59	1	0	1	1	1	0	1	1
-8	1	0	0	0	1	0	0	0	-60	1	0	1	1	1	1	0	0
-9	1	0	0	0	1	0	0	1	-61	1	0	1	1	1	1	0	1
-10	1	0	0	0	1	0	1	0	-62	1	0	1	1	1	1	1	0
-11	1	0	0	0	1	0	1	1	-63	1	0	1	1	1	1	1	1
-12	1	0	0	0	1	1	0	0	-64	1	1	0	0	0	0	0	0
-13	1	0	0	0	1	1	0	1	-65	1	1	0	0	0	0	0	1
-14	1	0	0	0	1	1	1	0	-66	1	1	0	0	0	0	1	0
-15	1	0	0	0	1	1	1	1	-67	1	1	0	0	0	0	1	1
-16	1	0	0	1	0	0	0	0	-68	1	1	0	0	0	1	0	0
-17	1	0	0	1	0	0	0	1	-69	1	1	0	0	0	1	0	1
-18	1	0	0	1	0	0	1	0	-70		1	0	0	0	1	1	0
-19	1	0	0	1	0	0	1	1	-71	1	1	0	0	0	1	1	1
-20	1	0	0	1	0	1	0	0	-72	1	1	0	0	1	0	0	0
-20	1	0	0	1	0	1	0	1	-72	1	1	0	0	1	0	0	1
-21	1	0	0	1	0	1	1	0	-73	1	1	0	0	1	0	1	0
-22	1	0	0	1	0	1	1	1	-74	1	1	0	0	1	0	1	1
-23	1	0	0	1	1	0	0	0	-75	1	1	0	0	1	1	0	0
-24 -25	1	0		1	1			1		1	1	0	0		1	-	1
		-	0			0	0		-77			-	-	1		0	
-26	1	0	0	1	1	0	1	0	-78	1	1	0	0	1	1	1	0
-27	1	0	0	1	1	0	1	1	-79	1	1	0	0	1	1	1	1
-28	1	0	0	1	1	1	0	0	-∞	1	1	1	1	1	1	1	1

:Initial condition

#### About advanced switch circuit

- [1] Advanced switch technology
- 1-1. Advanced switch effects

Advanced switch technology is Rohm original switching pop noise prevention technology. The audible signal is discontinuous during the gain switching instantly which cause the noise to occur. This Advanced switch circuit will prevent this discontinuous signal by completing the signal waveform and will significantly reduce the noise.

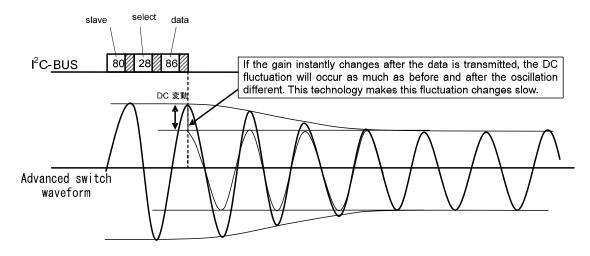


Figure 16. Advanced switch wave

This Advanced switch technology will start the switching when received the signal sent from the micon. At any constant time, the switching waveform is shown as above figure. This IC will optimally operate by internally processing the data sent from the micon to prevent the switching shock.

However, sometimes the switching waveform is not like the intended form depends on the transmission timing. Therefore, below is the example of the relationship between the transmission timing and actual switching time. Please consider this relationship for the setting.

- 1-2. The kind of the Transferring Data
  - Data setting other than Advanced switch supported items ( P.9 Select Address and data Data format without hatching) There is no particular rule about transferring data.
  - Advanced switch supported items data setting (P.9 Select Address and data Data format with hatching) There is no particular rule about transferring data, but Advanced switch must follow the switching sequence as mentioned in [2].
- X Advanced switch supported blocks are "Volume" and " EXT ON/OFF" (In detail, please refer p9).

[2] Data transmission of Advanced switch supported items 2-1. Switching time of Advanced switch

Switching time includes [Twait(Wait time)], [Tsft( $A \rightarrow B$  switching time)] and [Tsft( $B \rightarrow A$  switching time)]. 25msec is needed per 1 switching. (Tsoft = Twait + 2 \* Tsft, Twait=2.3msec, Tsft=11.2msec)

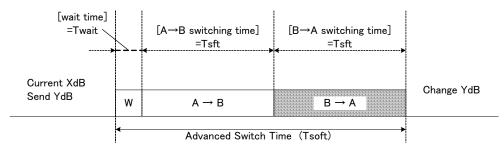


Figure 17. About Advanced switching time

In Figure 8, Start/Stop state is expressed as "A" and temporary state is expressed as "B".

The switching sequence of Advance switch will be,  $A(\text{start}) \rightarrow B \rightarrow A(\text{stop})$ , thus switching will not stop at B state. In other words, switching is performed from  $A(\text{Initial gain}) \rightarrow B(\text{set gain} \rightarrow A(\text{set gain}))$  when switching from initial gain to set gain.

It is possible to change the switching time of Advanced switch time by setting the EXT Advanced switch multi sel and Advanced Switch Time of EXT at select Address2.

If only <u>EXT ON/OFF</u> is performed in all Advanced switch operation, the switching time of Advanced switch is determined by EXT Advanced switch multi sel and Advanced Switch Time of EXT.

#### For example

EXT Advanced switch multi sel is set to x8 and Advanced Switch Time of EXT is set to 14.4msec In this case, the switching time of Advanced switch is determined as below.

EXT Advanced switch multi sel x Advanced Switch Time of EXT = 115.2msec

This is equal to switching time of  $A \rightarrow B$  or  $B \rightarrow A(Tsft)$ .

As mentioned in Figure 11 (Start sequence of Advanced switch), each ch(6channels) volume and EXT ON/OFF switch at the same timing. When each ch(6channels) volume switches at the same time EXT ON/OFF operation is performed, switching time of each ch(6channels) volume will be the same as EXT ON/OFF switching set by calculation above. In other words, switching time of EXT ON/OFF has higher priority than that of the 6channels volume

Even if switching time of EXT ON/OFF is set by calculation above, when EXT ON/OFF switching is not being performed, switching time of each ch(6channels) volume is determined as Tsft=11.2msec. Please exercise caution when setting the switching time of Advanced switch.

2-2. Explanation on data transmission's timing and switching operation.

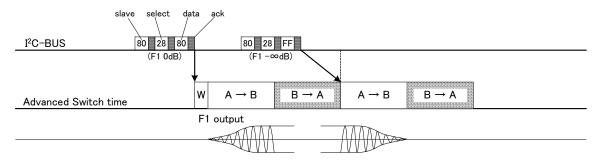
The following examples show the time chart from the time a data is transmitted until the switching starts.

Transmission example 1 This is an example when transmitting data in same block with enough transmission interval. This enough interval refers to the tolerance margin time of Tsoft multiplied by 1.4.

slave	e select da	ta ack	
I <sup>2</sup> C-BUS	80 28 80	80 28 FF	
Advanced Switch time	(F1 0dB)	$(F1 - \infty dB)$ $Tsoft * 1.4 msec$ $W A \rightarrow B B \rightarrow A$	$\begin{array}{c} \bullet \\ W \\ A \rightarrow B \\ B \rightarrow A \end{array}$
Advanced Switch Line		F1 output	

■ Transmission example 2

This is an example when the transmission interval is not enough (smaller than transmission example 1). When the data is transmitted during the first switching operation, the second data transmission will continue after complete the first switching. In this case, there is no wait time (Twait) before the second switching.

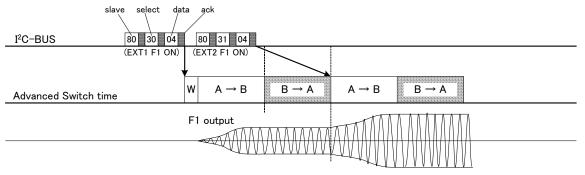


Transmission example 3

This is an example when transmission interval is even smaller (smaller than transmission example 2). When the data is transmitted during the first switching, and it is during  $A \rightarrow B$  switching operation, if the transmitted data is volume, switching of new data is performed at  $B \rightarrow A$  timing

I <sup>2</sup> C-BUS	data ack 80 28 FF	
(F1 0dB)	(F1 -∞dB) \	
	¥	
Advanced Switch time	$W \qquad A \to B \qquad B \to A$	

If the transmitted data is EXT ON/OFF switching, when other switching data is sent during  $A \rightarrow B$  switching, switching's will be the same as Transmission example 2



About data transmission to multi-channels, there is a caution. It is possible that Lch and Rch in same block(Front/Rear/Sub) can be switched at the same timing. For example, when the data transmission is set as the figure below, it is possible that OUTF1 and OUTF2 can be switched at the same timing(Data II is sent for FL (Lch) and data II is sent for FR (Rch)). Please take note that Twait is wait time for starting switching and designed to 2.3msec. (Considering fluctuation of element, Twait may change from 1.2msec (Min.) to 4.6msec (Max.).

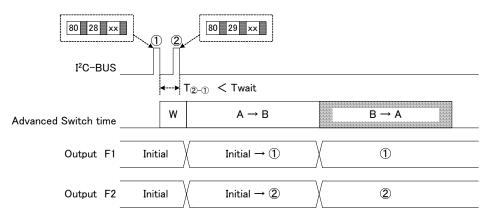


Figure 18. The operation during multi-channels (1ch, 2ch) data transmission (smaller than Twait interval).

Next, when data 2 is not transmitted during the Twait, the switching operation is as following figure.

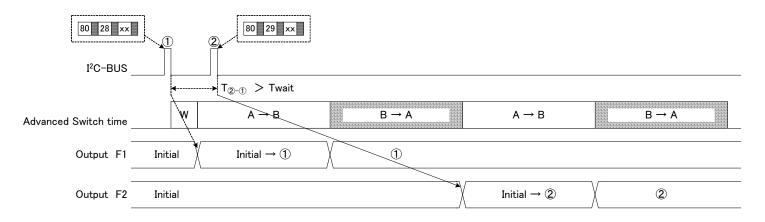
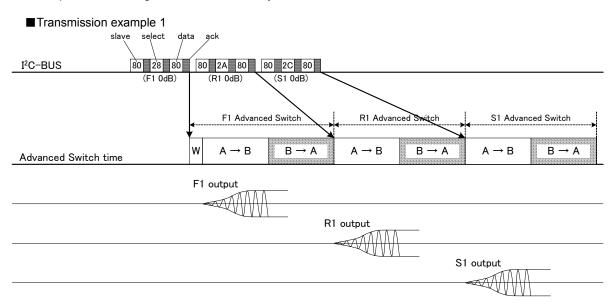


Figure 19. The operation during multi-channels (1ch, 2ch) data transmission (larger than Twait interval).

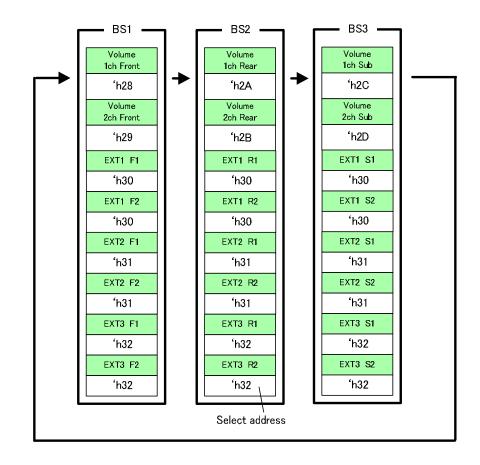
2-3. Multi-blocks data transmission timing and switching operation.

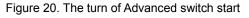
In case the data is transmitted to the multi-blocks, the processing is performed internally by BS unit. Micro step volume starting order is determined by BS unit.



XIt is the same even if it transfers data in auto increment mode.

There are no timing regulations of I<sup>2</sup>C-BUS transferring data. But the timing of a change start after the end of the present change. In addition, the timing of Advanced switch is not depended of a transferring data turn, but conforms in turn of the following figure.





 $\ensuremath{\textup{\ensuremath{\mathbb{X}}}}\xspace{The block}$  in the same group can start the Advanced switch in the same time.

	ion example 2 the transmission order is	different with actual switching ord	er.	
I <sup>2</sup> C-BUS			①F1 -6dB ②F1 -20dB ③S1 -6dB ④R1 -6dB	
	F1 Advanced Sv	vitch R1 Advanced Switch	S1 Advanced Switch	F1 Advanced Switch
Advanced Switch time	$W \qquad A \rightarrow B$	$B \to A \qquad A \to B \qquad B \to A$	$A \to B \qquad B \to A$	$A \to B \qquad B \to A$
Output F1	Initial $\checkmark$ Initial $\rightarrow$ (1)	0		$(1) \rightarrow 2$ 2
Output R1	Initial	$\left< \text{Initial} \rightarrow \textcircled{4} \right>$	4	
Output S1	Initial		$\left< \text{Initial} \rightarrow \bigcirc \right> \right>$	3

During Front switching, in case of Front/Rear/SW continuously received, Rear and SW switching are the priority. If you want the switching starts as the data transmission order, please transmit the next data after current switching is ended.

■Transmission example 3

For Refresh data, the IC will internally judge that there is no difference with the current data setting and therefore gain switching operation will not start.

Continuing the Refresh data and transmit the other block data.

	slave select	data a	ack					
I <sup>2</sup> C-BUS	80 28 80				80 28 80	80 2A 80		
	(F1 0dB)				(F1_0dB)	(R1 0dB)		
					Refresh Data			
		<b>_</b>	F1 Advand	ced Switch			R1 Adva	nced Switch
Advanced Switch ti	me	w	$A\toB$	$B \rightarrow A$			$A \rightarrow B$	$B \rightarrow A$

#### **Application Circuit Diagram**

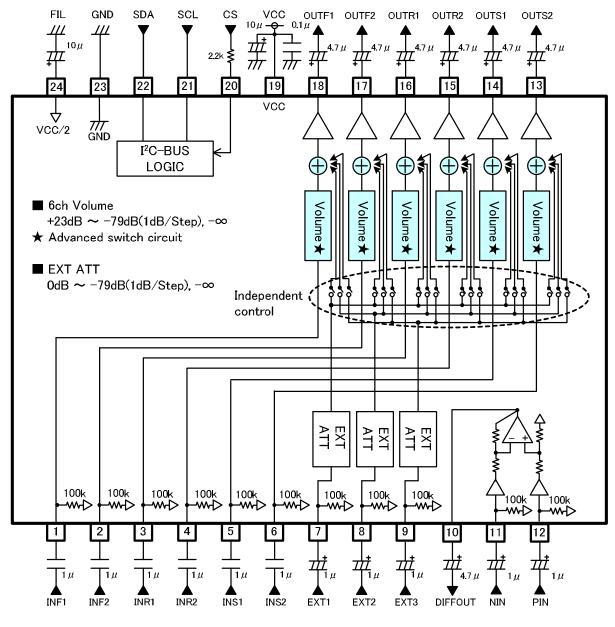


Figure 21. Application Circuit Diagram



#### Notes on wiring

Delease connect the decoupling capacitor of the power supply in the shortest distance as much as possible to VCC and GND, VEE.

②Lines of GND shall be one-point connected.

③Wiring pattern of Dagital shall be away from the analog unit and cross-talk is not acceptable.

(Lines of SCL and SDA of I<sup>2</sup>C BUS shall not be parallel if possible. The lines shall be shielded, if they are adjacent to each other.

(5)Lines of analog input shall not be parallel if possible. The lines shall be shielded, if they are adjacent to each other.

#### **Power Dissipation**

Thermal design for the IC

Temperature has great influence to the IC characteristics, and exceeding the absolute maximum ratings may degrade and damage the IC. A proper consideration must be given from two points, immediate damage and long-term reliability of operation.

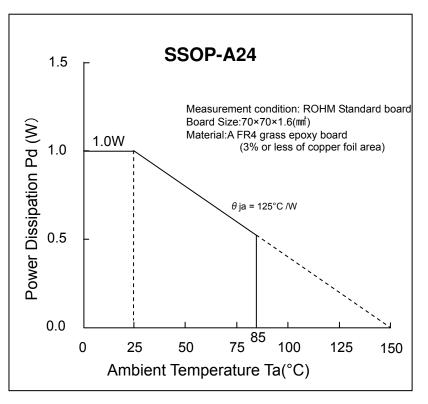


Figure 22. Temperature Derating Curve

Note) Values mentioned above are based on actual measurement, and not guaranteed. Note) Power dissipation value varies depending to the board on which the IC is mounted. Terminal Equivalent Circuit and Description

		it and Descri	Stion	
Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6 7 8 9 11 12	INF1 INF2 INR1 INS2 INS1 INS2 EXT1 EXT2 EXT3 NIN PIN	4.25V		A terminal for signal input. The input impedance is 100kΩ(typ).
10 13 14 15 16 17 18	DIFFOUT OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25V		A terminal for fader output.
22	SCL	_	SCL GND GND	A terminal for clock input of I <sup>2</sup> C-BUS.
23	SDA	_	SDA GND GND	A terminal for data input of I <sup>2</sup> C-BUS.
20	CS	_	CS GND GND	CS Input Terminal. A terminal for Slave Address selection. "CS" is "High"→Slave Address "84 H" "CS" is "Low"→ Slave Address "80 H"

The figure in the pin explanation and input/output equivalent circuit is reference value, it's doesn't guarantee the value.

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
19	VCC	8.5V		Power supply terminal.
23	GND	0V		Ground terminal.
24	FIL	4.25V		1/2 VCC terminal. Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.

The figure in the pin explanation and input/output equivalent circuit is reference value, it's doesn't guarantee the value.

#### **Operational Notes**

#### 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

#### 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

#### 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

#### 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

#### 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

#### 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

#### 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

#### 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

#### 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

#### 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

#### 11. Unused Input Terminals

Because the input impedance of the terminal becomes  $100k\Omega$  when the signal input terminal makes a terminal open, the plunge noise from outside sometimes becomes a problem.

About unused input pin, please connect to GND through capacitor, or please set that channel MUTE. About unused output pin, it is no problem to set to open.

#### **Operational Notes – continued 1**

#### 12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

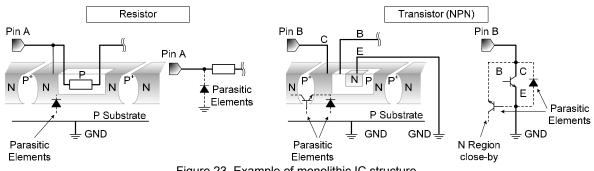


Figure 23. Example of monolithic IC structure

#### 13. Ceramic Capacitor

When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

#### 14. About power ON/OFF

At power ON/OFF, a pop sound will be generated and, therefore, use MUTE on the set.

**15.** About EXT ATT(Select Address 33, 34, 35(hex)) switching When switching EXT ATT, please set EXT OFF.

#### 16. About Volume gain switching, EXT ON/OFF switching

In case of the boost of the volume when changing to the high gain which exceeds +12dB especially, the switching pop noise sometimes becomes big. (For example, in case gain of the power amplifier is set to +26dB, and switching time is set to 11.2msec)

In this case, countermeasures as below are recommended to decrease this pop noise.

Switching gain by only 1dB/Step

· Increase switching time (In detail, please refer p9.)

#### **Operational Notes – continued 2**

16. About output load characteristics

The usage of load for output are below (reference). Please use the load more than  $10[k\Omega](TYP)$ .

Output terminal								
	Terminal							
	No.	Name	No.	Name	No.	Name	No.	Name
	18	OUTF1	16	OUTR1	14	OUTS1	10	DIFFOUT
	17	OUTF2	15	OUTR2	13	OUTS2		

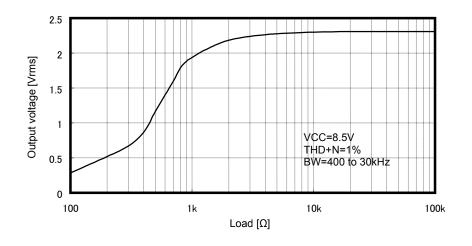
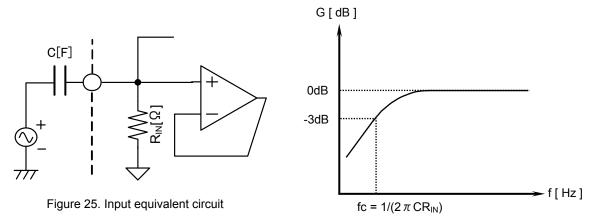


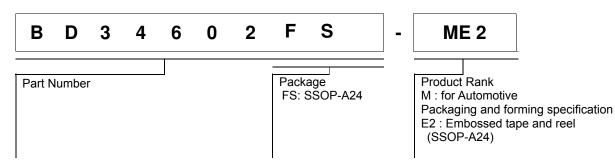
Figure 24. Output load characteristic VCC=8.5V (Reference)

#### 17. About constant set up of input coupling capacitor

In the signal input terminal, the constant setting of input coupling capacitor C(F) be sufficient input impedance  $R_{IN}$ (from 70 to 130k $\Omega$ ) inside IC and please decide. The first HPF characteristic of RC is composed.

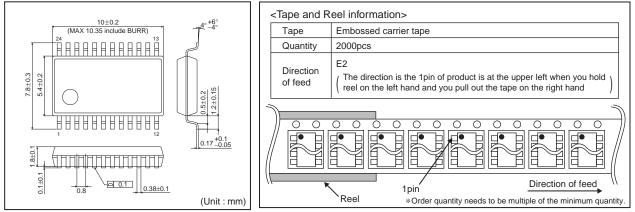


#### Ordering Information

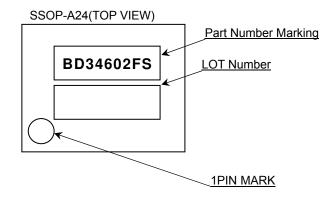


Physical Dimension, Tape and Reel Information

SSOP-A24



#### **Marking Diagrams**



#### **Revision History**

	Date	Revision	Changes					
ĺ	22.Oct.2015	001	New Release					

## Notice

#### Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA	
CLASSII	CLASSⅢ	CLASS II b	CLASSⅢ	
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:

[a] Installation of protection circuits or other protective devices to improve system safety

[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

#### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

#### **Precaution Regarding Intellectual Property Rights**

- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
- 2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
- 3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

#### **Other Precaution**

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- 2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
- 3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
- 4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

#### **General Precaution**

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in an y way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
- 2. All information contained in this docume nt is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sale s representative.
- 3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.